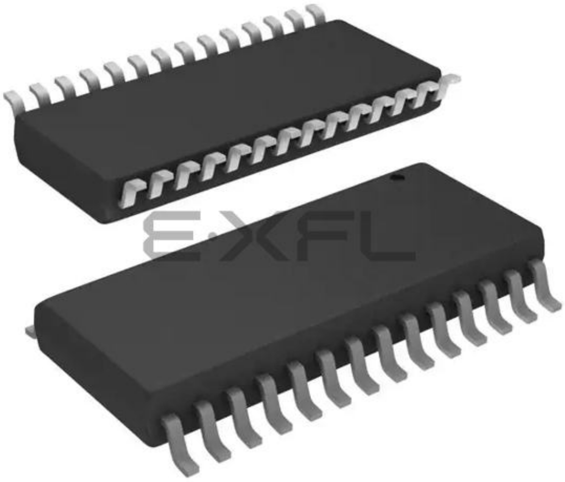


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

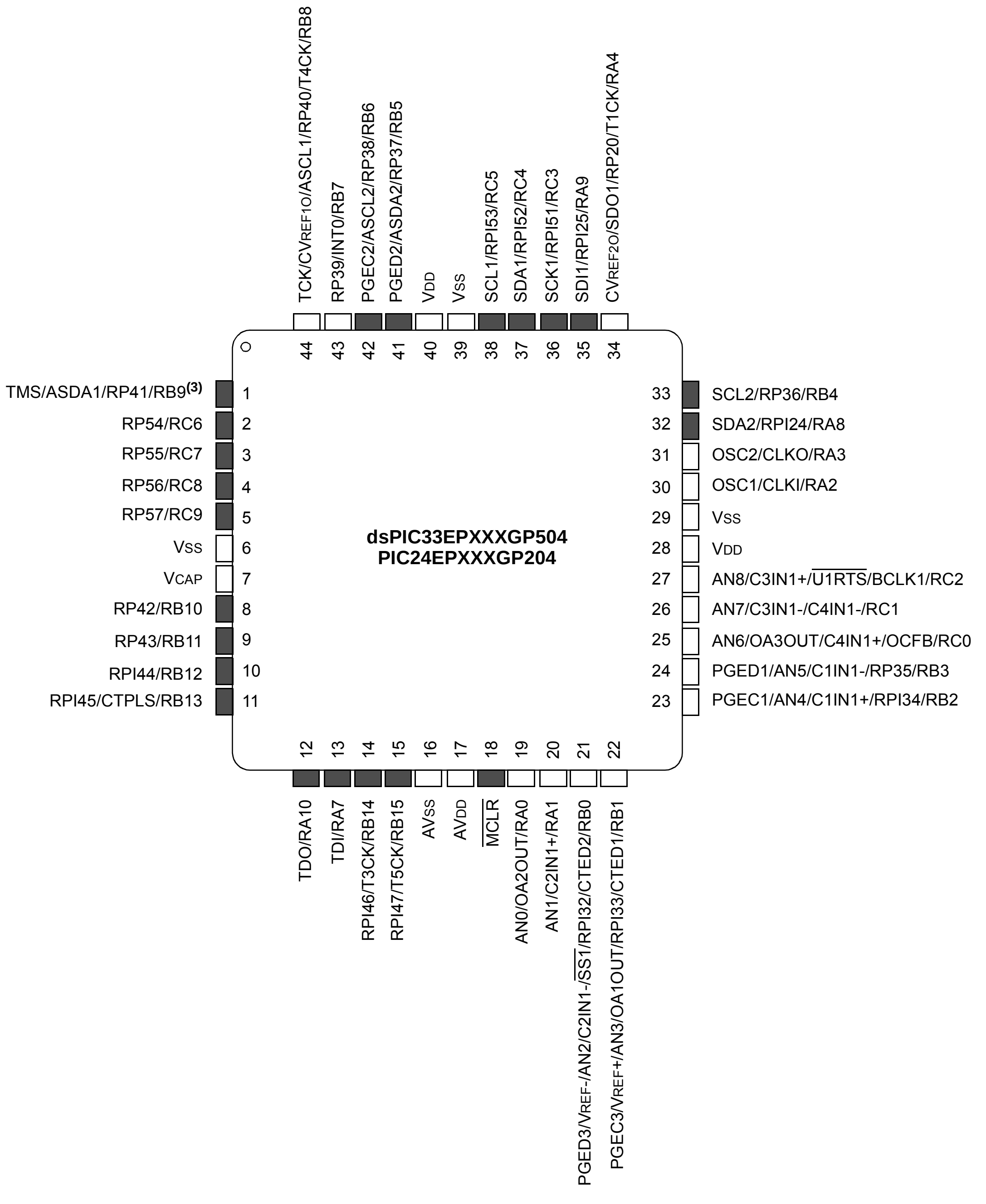
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc202t-e-so

Pin Diagrams (Continued)

44-Pin TQFP[1,2]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name[(4)]	Pin Type	Buffer Type	PPS	Description
C1IN1- C1IN2- C1IN1+ OA1OUT C1OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 1 Negative Input 1. Comparator 1 Negative Input 2. Op Amp/Comparator 1 Positive Input 1. Op Amp 1 output. Comparator 1 output.
C2IN1- C2IN2- C2IN1+ OA2OUT C2OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 2 Negative Input 1. Comparator 2 Negative Input 2. Op Amp/Comparator 2 Positive Input 1. Op Amp 2 output. Comparator 2 output.
C3IN1- C3IN2- C3IN1+ OA3OUT C3OUT	I I I O O	Analog Analog Analog Analog —	No No No No Yes	Op Amp/Comparator 3 Negative Input 1. Comparator 3 Negative Input 2. Op Amp/Comparator 3 Positive Input 1. Op Amp 3 output. Comparator 3 output.
C4IN1- C4IN1+ C4OUT	I I O	Analog Analog —	No No Yes	Comparator 4 Negative Input 1. Comparator 4 Positive Input 1. Comparator 4 output.
CVREF1O CVREF2O	O O	Analog Analog	No No	Op amp/comparator voltage reference output. Op amp/comparator voltage reference divided by 2 output.
PGED1 PGEC1 PGED2 PGEC2 PGED3 PGEC3	I/O I I/O I I/O I	ST ST ST ST ST ST	No No No No No No	Data I/O pin for Programming/Debugging Communication Channel 1. Clock input pin for Programming/Debugging Communication Channel 1. Data I/O pin for Programming/Debugging Communication Channel 2. Clock input pin for Programming/Debugging Communication Channel 2. Data I/O pin for Programming/Debugging Communication Channel 3. Clock input pin for Programming/Debugging Communication Channel 3.
$\overline{\text{MCLR}}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.
VREF+	I	Analog	No	Analog voltage reference (high) input.
VREF-	I	Analog	No	Analog voltage reference (low) input.

Legend:
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
PPS = Peripheral Pin Select
Analog = Analog input
O = Output
TTL = TTL input buffer
P = Power
I = Input

Note 1: This pin is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This pin is available on dsPIC33EPXXXGP/MC50X devices only.

3: This is the default Fault on Reset for dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices. See **Section 16.0 “High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”** for more information.

4: Not all pins are available in all packages variants. See the **“Pin Diagrams”** section for pin availability.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS AND MICROCONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used) (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Program Memory"** (DS70613) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture features separate program and data memory spaces, and buses. This architecture also allows the direct access of program memory from the Data Space (DS) during code execution.

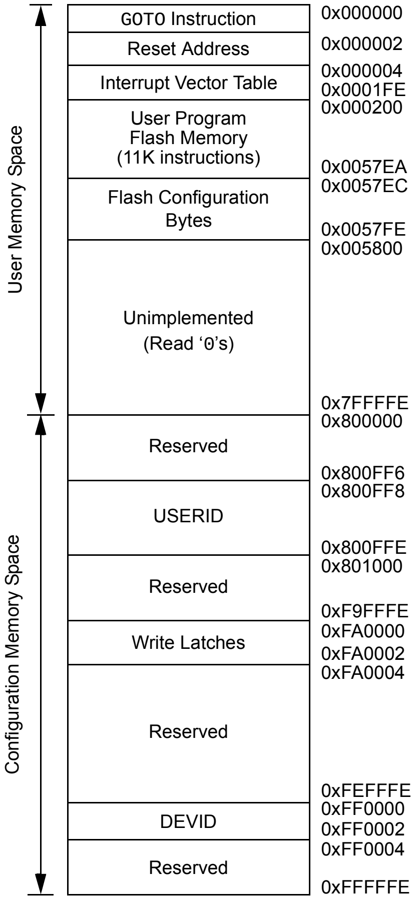
4.1 Program Address Space

The program address memory space of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit PC during program execution, or from table operation or Data Space remapping, as described in **Section 4.8 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of `TBLRD` operations, which use TBLPAG<7> to read Device ID sections of the configuration memory space.

The program memory maps, which are presented by device family and memory size, are shown in Figure 4-1 through Figure 4-5.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X AND PIC24EP32GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

6.1 Reset Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

6.1.1 KEY RESOURCES

- **"Reset"** (DS70602) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 11-15: RPINR37: PERIPHERAL PIN SELECT INPUT REGISTER 37 (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SYNCI1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14-8	**SYNCI1R<6:0>:** Assign PWM Synchronization Input 1 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS
bit 7-0	**Unimplemented:** Read as ‘`0`’

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits(4)

`11111` = No Sync or Trigger source for ICx
`11110` = Reserved
`11101` = Reserved
`11100` = CTMU module synchronizes or triggers ICx
`11011` = ADC1 module synchronizes or triggers ICx(5)
`11010` = CMP3 module synchronizes or triggers ICx(5)
`11001` = CMP2 module synchronizes or triggers ICx(5)
`11000` = CMP1 module synchronizes or triggers ICx(5)
`10111` = Reserved
`10110` = Reserved
`10101` = Reserved
`10100` = Reserved
`10011` = IC4 module synchronizes or triggers ICx
`10010` = IC3 module synchronizes or triggers ICx
`10001` = IC2 module synchronizes or triggers ICx
`10000` = IC1 module synchronizes or triggers ICx
`01111` = Timer5 synchronizes or triggers ICx
`01110` = Timer4 synchronizes or triggers ICx
`01101` = Timer3 synchronizes or triggers ICx **(default)**
`01100` = Timer2 synchronizes or triggers ICx
`01011` = Timer1 synchronizes or triggers ICx
`01010` = PTGOx module synchronizes or triggers ICx(6)
`01001` = Reserved
`01000` = Reserved
`00111` = Reserved
`00110` = Reserved
`00101` = Reserved
`00100` = OC4 module synchronizes or triggers ICx
`00011` = OC3 module synchronizes or triggers ICx
`00010` = OC2 module synchronizes or triggers ICx
`00001` = OC1 module synchronizes or triggers ICx
`00000` = No Sync or Trigger source for ICx

Note 1: The IC32 bit in both the Odd and Even IC must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits). It can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x (ICx) module has one PTG input source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO8 = IC1
PTGO9 = IC2
PTGO10 = IC3
PTGO11 = IC4

REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER

R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**ACKSTAT:** Acknowledge Status bit (when operating as I^{2}C™ master, applicable to master transmit operation) `1` = NACK received from slave `0` = ACK received from slave Hardware is set or clear at the end of slave Acknowledge.
bit 14	**TRSTAT:** Transmit Status bit (when operating as I^{2}C master, applicable to master transmit operation) `1` = Master transmit is in progress (8 bits + ACK) `0` = Master transmit is not in progress Hardware is set at the beginning of master transmission. Hardware is clear at the end of slave Acknowledge.
bit 13-11	**Unimplemented:** Read as ‘`0`’
bit 10	**BCL:** Master Bus Collision Detect bit `1` = A bus collision has been detected during a master operation `0` = No bus collision detected Hardware is set at detection of a bus collision.
bit 9	**GCSTAT:** General Call Status bit `1` = General call address was received `0` = General call address was not received Hardware is set when address matches general call address. Hardware is clear at Stop detection.
bit 8	**ADD10:** 10-Bit Address Status bit `1` = 10-bit address was matched `0` = 10-bit address was not matched Hardware is set at the match of the 2nd byte of the matched 10-bit address. Hardware is clear at Stop detection.
bit 7	**IWCOL:** I2Cx Write Collision Detect bit `1` = An attempt to write to the I2CxTRN register failed because the I^{2}C module is busy `0` = No collision Hardware is set at the occurrence of a write to I2CxTRN while busy (cleared by software).
bit 6	**I2COV:** I2Cx Receive Overflow Flag bit `1` = A byte was received while the I2CxRCV register was still holding the previous byte `0` = No overflow Hardware is set at an attempt to transfer I2CxRSR to I2CxRCV (cleared by software).
bit 5	**D_A:** Data/Address bit (when operating as I^{2}C slave) `1` = Indicates that the last byte received was data `0` = Indicates that the last byte received was a device address Hardware is clear at a device address match. Hardware is set by reception of a slave byte.
bit 4	**P:** Stop bit `1` = Indicates that a Stop bit has been detected last `0` = Stop bit was not detected last Hardware is set or clear when a Start, Repeated Start or Stop is detected.

20.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"UART"** (DS70582) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two UART modules.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family. The UART is a full-duplex, asynchronous system that can communicate with peripheral devices, such as personal computers, LIN/J2602, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the UxCTS and UxRTS pins, and also includes an IrDA® encoder and decoder.

Note: Hardware flow control using UxRTS and UxCTS is not available on all pin count devices. See the **"Pin Diagrams"** section for availability.

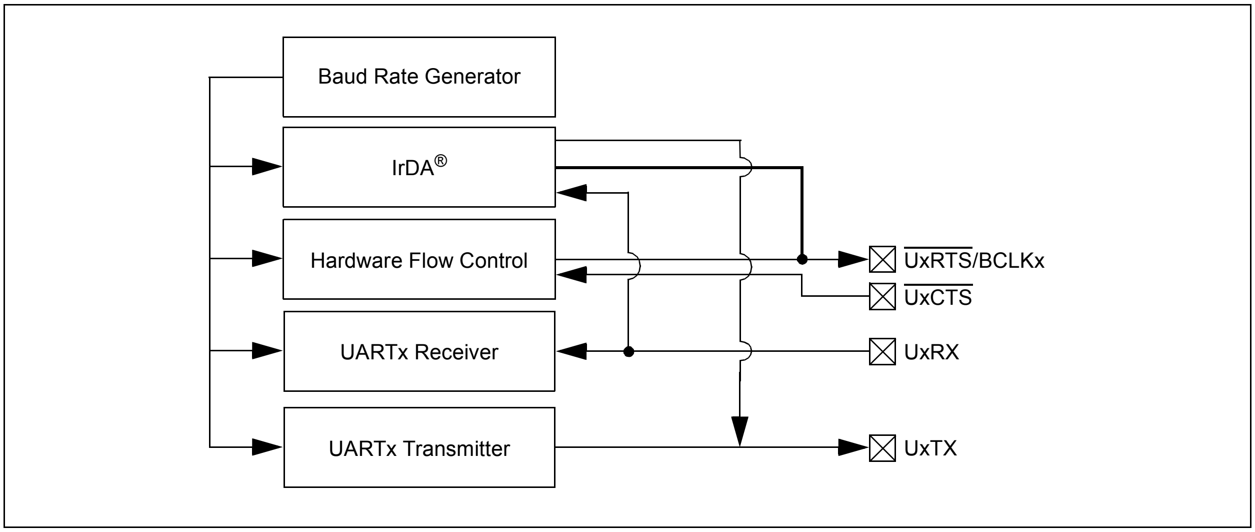
The primary features of the UARTx module are:

- Full-Duplex, 8 or 9-Bit Data Transmission through the UxTX and UxRX Pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with UxCTS and UxRTS Pins
- Fully Integrated Baud Rate Generator with 16-Bit Prescaler
- Baud Rates Ranging from 4.375 Mbps to 67 bps at 16x mode at 70 MIPS
- Baud Rates Ranging from 17.5 Mbps to 267 bps at 4x mode at 70 MIPS
- 4-Deep First-In First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive Interrupts
- A Separate Interrupt for all UARTx Error Conditions
- Loopback mode for Diagnostic Support
- Support for Sync and Break Characters
- Support for Automatic Baud Rate Detection
- IrDA® Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA Support

A simplified block diagram of the UARTx module is shown in Figure 20-1. The UARTx module consists of these key hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 20-1: UARTx SIMPLIFIED BLOCK DIAGRAM



20.3 UARTx Control Registers

REGISTER 20-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)

1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
0 = UARTx is disabled; all UARTx pins are controlled by PORT latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **USIDL:** UARTx Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)

1 = IrDA encoder and decoder are enabled
0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit

1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as ‘0’

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits

11 = UxTX, UxRX and BCLKx pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(3)
10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used(4)
01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(4)
00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLKx pins are controlled by PORT latches

bit 7 **WAKE:** Wake-up on Start bit Detect During Sleep Mode Enable bit

1 = UARTx continues to sample the UxRX pin; interrupt is generated on the falling edge; bit is cleared in hardware on the following rising edge
0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit

1 = Enables Loopback mode
0 = Loopback mode is disabled

Note 1: Refer to the **“UART”** (DS70582) section in the *“dsPIC33/PIC24 Family Reference Manual”* for information on enabling the UARTx module for receive or transmit operation.
2: This feature is only available for the 16x BRG mode (BRGH = 0).
3: This feature is only available on 44-pin and 64-pin devices.
4: This feature is only available on 64-pin devices.

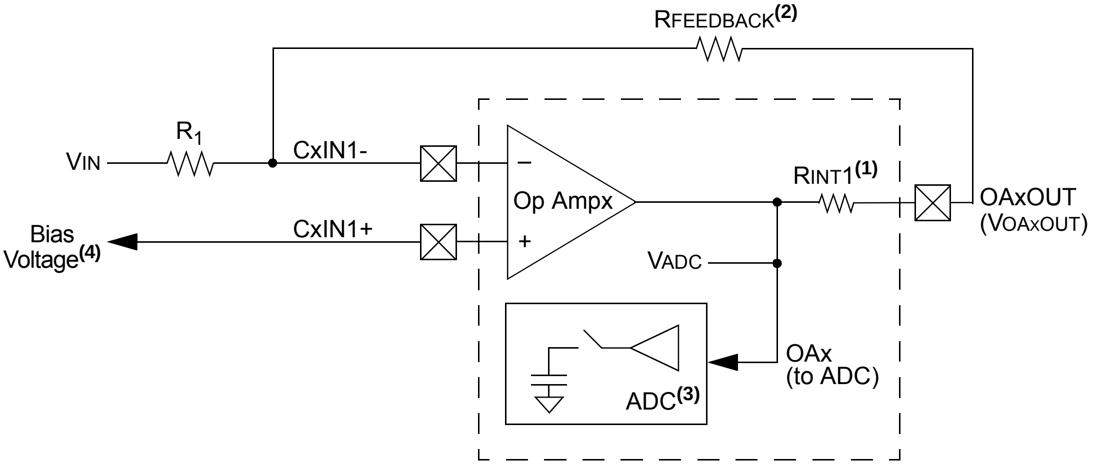
25.1 Op Amp Application Considerations

There are two configurations to take into consideration when designing with the op amp modules that are available in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices. Configuration A (see Figure 25-6) takes advantage of the internal connection to the ADC module to route the output of the op amp directly to the ADC for measurement. Configuration B (see Figure 25-7) requires that the designer externally route the output of the op amp (OAxOUT) to a separate analog input pin (ANy) on the device. Table 30-55 in **Section 30.0 "Electrical Characteristics"** describes the performance characteristics for the op amps, distinguishing between the two configuration types where applicable.

25.1.1 OP AMP CONFIGURATION A

Figure 25-6 shows a typical inverting amplifier circuit taking advantage of the internal connections from the op amp output to the input of the ADC. The advantage of this configuration is that the user does not need to consume another analog input (ANy) on the device, and allows the user to simultaneously sample all three op amps with the ADC module, if needed. However, the presence of the internal resistance, RINT1, adds an error in the feedback path. Since RINT1 is an internal resistance, in relation to the op amp output (VOAXOUT) and ADC internal connection (VADC), RINT1 must be included in the numerator term of the transfer function. See Table 30-53 in **Section 30.0 "Electrical Characteristics"** for the typical value of RINT1. Table 30-60 and Table 30-61 in **Section 30.0 "Electrical Characteristics"** describe the minimum sample time (TSAMP) requirements for the ADC module in this configuration. Figure 25-6 also defines the equations that should be used when calculating the expected voltages at points, VADC and VOAXOUT.

FIGURE 25-6: OP AMP CONFIGURATION A



$$V_{ADC} = \left(\frac{R_{FEEDBACK} + R_{INT1}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

$$V_{OAxOUT} = \left(\frac{R_{FEEDBACK}}{R_1}\right)(\ Bias\ Voltage - V_{IN}\ )$$

Note 1: See Table 30-53 for the Typical value.

2: See Table 30-53 for the Minimum value for the feedback resistor.

3: See Table 30-60 and Table 30-61 for the minimum sample time (TSAMP).

4: CVREF1O or CVREF2O are two options that are available for supplying bias voltage to the op amps.

REGISTER 25-6: CMxFLTR: COMPARATOR x FILTER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘`0`’

bit 6-4 **CFSEL<2:0>:** Comparator Filter Input Clock Select bits

`111` = T5CLK[1]
`110` = T4CLK[2]
`101` = T3CLK[1]
`100` = T2CLK[2]
`011` = Reserved
`010` = SYNCO1[3]
`001` = FOSC[4]
`000` = FP[4]

bit 3 **CFLTREN:** Comparator Filter Enable bit

`1` = Digital filter is enabled
`0` = Digital filter is disabled

bit 2-0 **CFDIV<2:0>:** Comparator Filter Clock Divide Select bits

`111` = Clock Divide 1:128
`110` = Clock Divide 1:64
`101` = Clock Divide 1:32
`100` = Clock Divide 1:16
`011` = Clock Divide 1:8
`010` = Clock Divide 1:4
`001` = Clock Divide 1:2
`000` = Clock Divide 1:1

Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

TABLE 27-1: CONFIGURATION BYTE REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reserved	0057EC	32	—	—	—	—	—	—	—	—	—
	00AFEC	64									
	0157EC	128									
	02AFEC	256									
	0557EC	512									
Reserved	0057EE	32	—	—	—	—	—	—	—	—	—
	00AFEE	64									
	0157EE	128									
	02AFEE	256									
	0557EE	512									
FICD	0057F0	32	—	Reserved(3)	—	JTAGEN	Reserved(2)	Reserved(3)	—	ICS<1:0>	
	00AFF0	64									
	0157F0	128									
	02AFF0	256									
	0557F0	512									
FPOR	0057F2	32	—	WDTWIN<1:0>		ALTI2C2	ALTI2C1	Reserved(3)	—	—	—
	00AFF2	64									
	0157F2	128									
	02AFF2	256									
	0557F2	512									
FWDT	0057F4	32	—	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST<3:0>			
	00AFF4	64									
	0157F4	128									
	02AFF4	256									
	0557F4	512									
FOSC	0057F6	32	—	FCKSM<1:0>		IOL1WAY	—	—	OSCIOFNC	POSCMD<1:0>	
	00AFF6	64									
	0157F6	128									
	02AFF6	256									
	0557F6	512									
FOSCSEL	0057F8	32	—	IESO	PWMLOCK(1)	—	—	—	FNOSC<2:0>		
	00AFF8	64									
	0157F8	128									
	02AFF8	256									
	0557F8	512									
FGS	0057FA	32	—	—	—	—	—	—	—	GCP	GWRP
	00AFFA	64									
	0157FA	128									
	02AFFA	256									
	0557FA	512									
Reserved	0057FC	32	—	—	—	—	—	—	—	—	—
	00AFFC	64									
	0157FC	128									
	02AFFC	256									
	0557FC	512									
Reserved	057FFE	32	—	—	—	—	—	—	—	—	—
	00AFFE	64									
	0157FE	128									
	02AFFE	256									
	0557FE	512									

Legend: — = unimplemented, read as ‘1’.

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This bit is reserved and must be programmed as ‘0’.

3: These bits are reserved and must be programmed as ‘1’.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
53	NEG	NEG Acc(1)	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG f	f = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG f,WREG	WREG = $\overline{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
54	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
55	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
56	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
57	PWRSAV	PWRSAV #lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL Expr	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT #lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
60	RESET	RESET	Software device Reset	1	1	None
61	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW #lit10,Wn	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN	Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
65	RLNC	RLNC f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
66	RRC	RRC f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z
67	RRNC	RRNC f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
68	SAC	SAC Acc,#Slit4,Wdo(1)	Store Accumulator	1	1	None
		SAC.R Acc,#Slit4,Wdo(1)	Store Rounded Accumulator	1	1	None
69	SE	SE Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
70	SETM	SETM f	f = 0xFFFF	1	1	None
		SETM WREG	WREG = 0xFFFF	1	1	None
		SETM Ws	Ws = 0xFFFF	1	1	None
71	SFTAC	SFTAC Acc,Wn(1)	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC Acc,#Slit6(1)	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
72	SL	SL f	f = Left Shift f	1	1	C,N,OV,Z
		SL f,WREG	WREG = Left Shift f	1	1	C,N,OV,Z
		SL Ws,Wd	Wd = Left Shift Ws	1	1	C,N,OV,Z
		SL Wb,Wns,Wnd	Wnd = Left Shift Wb by Wns	1	1	N,Z
		SL Wb,#lit5,Wnd	Wnd = Left Shift Wb by lit5	1	1	N,Z
73	SUB	SUB Acc(1)	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		SUB f	f = f – WREG	1	1	C,DC,N,OV,Z
		SUB f,WREG	WREG = f – WREG	1	1	C,DC,N,OV,Z
		SUB #lit10,Wn	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		SUB Wb,Ws,Wd	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		SUB Wb,#lit5,Wd	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
74	SUBB	SUBB f	f = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBB f,WREG	WREG = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBB #lit10,Wn	Wn = Wn – lit10 – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBB Wb,Ws,Wd	Wd = Wb – Ws – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBB Wb,#lit5,Wd	Wd = Wb – lit5 – $(\overline{C})$	1	1	C,DC,N,OV,Z
75	SUBR	SUBR f	f = WREG – f	1	1	C,DC,N,OV,Z
		SUBR f,WREG	WREG = WREG – f	1	1	C,DC,N,OV,Z
		SUBR Wb,Ws,Wd	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		SUBR Wb,#lit5,Wd	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
76	SUBBR	SUBBR f	f = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBBR f,WREG	WREG = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBBR Wb,Ws,Wd	Wd = Ws – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
		SUBBR Wb,#lit5,Wd	Wd = lit5 – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
77	SWAP	SWAP.b Wn	Wn = nibble swap Wn	1	1	None
		SWAP Wn	Wn = byte swap Wn	1	1	None
78	TBLRDH	TBLRDH Ws,Wd	Read Prog<23:16> to Wd<7:0>	1	5	None
79	TBLRDL	TBLRDL Ws,Wd	Read Prog<15:0> to Wd	1	5	None
80	TBLWTH	TBLWTH Ws,Wd	Write Ws<7:0> to Prog<23:16>	1	2	None
81	TBLWTL	TBLWTL Ws,Wd	Write Ws to Prog<15:0>	1	2	None
82	ULNK	ULNK	Unlink Frame Pointer	1	1	SFA
83	XOR	XOR f	f = f .XOR. WREG	1	1	N,Z
		XOR f,WREG	WREG = f .XOR. WREG	1	1	N,Z
		XOR #lit10,Wn	Wd = lit10 .XOR. Wd	1	1	N,Z
		XOR Wb,Ws,Wd	Wd = Wb .XOR. Ws	1	1	N,Z
		XOR Wb,#lit5,Wd	Wd = Wb .XOR. lit5	1	1	N,Z
84	ZE	ZE Ws,Wnd	Wnd = Zero-extend Ws	1	1	C,Z,N

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-12: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40°C \le T_A \le +85°C$ for Industrial $-40°C \le T_A \le +125°C$ for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	V_{OL}	**Output Low Voltage** 4x Sink Driver Pins(2)	—	—	0.4	V	V_{DD} = 3.3V, $I_{OL} \le 6$ mA, $-40°C \le T_A \le +85°C$ $I_{OL} \le 5$ mA, $+85°C < T_A \le +125°C$
		Output Low Voltage 8x Sink Driver Pins(3)	—	—	0.4	V	V_{DD} = 3.3V, $I_{OL} \le 12$ mA, $-40°C \le T_A \le +85°C$ $I_{OL} \le 8$ mA, $+85°C < T_A \le +125°C$
DO20	V_{OH}	**Output High Voltage** 4x Source Driver Pins(2)	2.4	—	—	V	$I_{OH} \ge -10$ mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins(3)	2.4	—	—	V	$I_{OH} \ge -15$ mA, V_{DD} = 3.3V
DO20A	V_{OH1}	**Output High Voltage** 4x Source Driver Pins(2)	1.5(1)	—	—	V	$I_{OH} \ge -14$ mA, V_{DD} = 3.3V
			2.0(1)	—	—		$I_{OH} \ge -12$ mA, V_{DD} = 3.3V
			3.0(1)	—	—		$I_{OH} \ge -7$ mA, V_{DD} = 3.3V
		Output High Voltage 8x Source Driver Pins(3)	1.5(1)	—	—	V	$I_{OH} \ge -22$ mA, V_{DD} = 3.3V
			2.0(1)	—	—		$I_{OH} \ge -18$ mA, V_{DD} = 3.3V
			3.0(1)	—	—		$I_{OH} \ge -10$ mA, V_{DD} = 3.3V

Note 1: Parameters are characterized but not tested.

2: Includes all I/O pins that are not 8x Sink Driver pins (see below).

3: Includes the following pins:
For devices with less than 64 pins: RA3, RA4, RA9, RB<7:15> and RC3
For 64-pin devices: RA4, RA9, RB<7:15>, RC3 and RC15

TABLE 30-13: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature $-40°C \le T_A \le +85°C$ for Industrial $-40°C \le T_A \le +125°C$ for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.(2)**	**Typ.**	**Max.**	**Units**	**Conditions**
BO10	V_{BOR}	BOR Event on V_{DD} Transition High-to-Low	2.65	—	2.95	V	V_{DD} **(Notes 2** and **3)**

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance.

2: Parameters are for design guidance only and are not tested in manufacturing.

3: The V_{BOR} specification is relative to V_{DD}.

TABLE 30-39: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `1`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-21: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

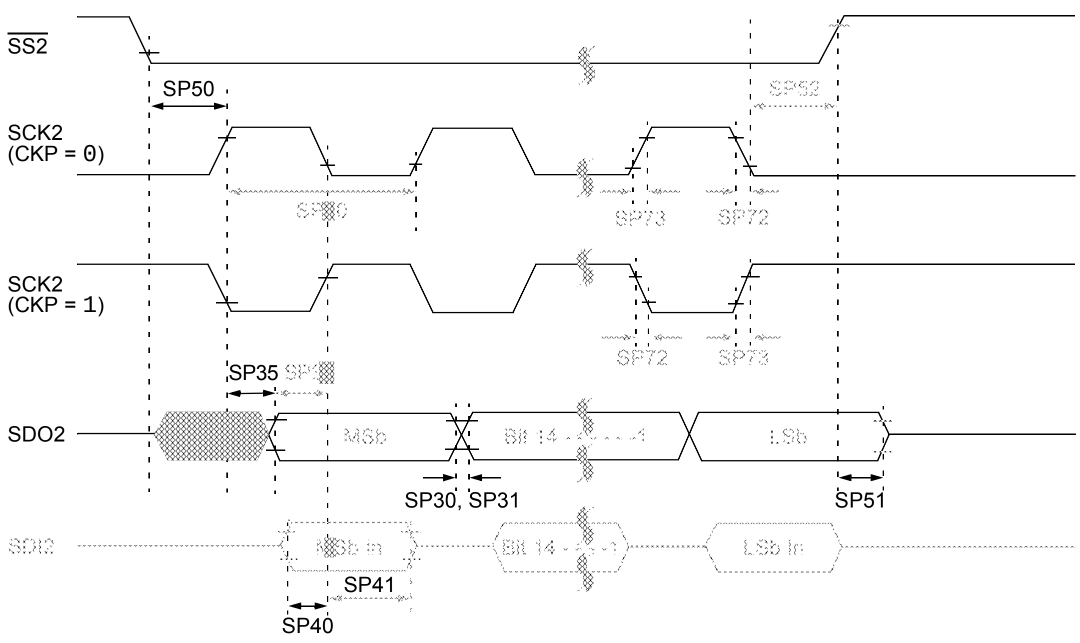


TABLE 30-50: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param. No.	**Symbol**	**Characteristic(3)**		**Min.**	**Max.**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode(1)	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25		µs	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	
IS51	TPGD	Pulse Gobbler Delay		65	390	ns	**(Note 2)**

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

2: Typical value for this parameter is 130 ns.

3: These parameters are characterized, but not tested in manufacturing.

Revision E (April 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-4: MAJOR SECTION UPDATES

Section Name	Update Description
"16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog"	The following 512-Kbyte devices were added to the General Purpose Families table (see Table 1): • PIC24EP512GP202 • PIC24EP512GP204 • PIC24EP512GP206 • dsPIC33EP512GP502 • dsPIC33EP512GP504 • dsPIC33EP512GP506 The following 512-Kbyte devices were added to the Motor Control Families table (see Table 2): • PIC24EP512MC202 • PIC24EP512MC204 • PIC24EP512MC206 • dsPIC33EP512MC202 • dsPIC33EP512MC204 • dsPIC33EP512MC206 • dsPIC33EP512MC502 • dsPIC33EP512MC504 • dsPIC33EP512MC506 Certain Pin Diagrams were updated to include the new 512-Kbyte devices.
Section 4.0 "Memory Organization"	Added a Program Memory Map for the new 512-Kbyte devices (see Figure 4-4). Added a Data Memory Map for the new dsPIC 512-Kbyte devices (see Figure 4-11). Added a Data Memory Map for the new PIC24 512-Kbyte devices (see Figure 4-16).
Section 7.0 "Interrupt Controller"	Updated the VECNUM bits in the INTTREG register (see Register 7-7).
Section 11.0 "I/O Ports"	Added tip 6 to **Section 11.5 "I/O Helpful Tips"**.
Section 27.0 "Special Features"	The following modifications were made to the Configuration Byte Register Map (see Table 27-1): • Added the column Device Memory Size (Kbytes) • Removed Notes 1 through 4 • Added addresses for the new 512-Kbyte devices
Section 30.0 "Electrical Characteristics"	Updated the Minimum value for Parameter DC10 (see Table 30-4). Added Power-Down Current (Ipd) parameters for the new 512-Kbyte devices (see Table 30-8). Updated the Minimum value for Parameter CM34 (see Table 30-53). Updated the Minimum and Maximum values and the Conditions for paramteer SY12 (see Table 30-22).